

Product Specification

XBLW SN74HC175

Quad D-type flip-flop with reset

WEB | www.xinboleic.com

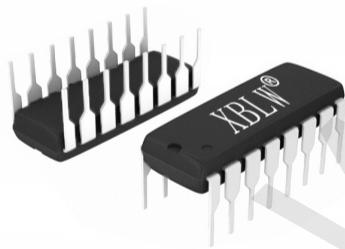


Description

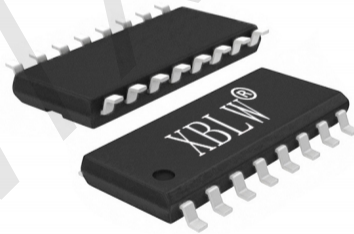
The SN74HC175 is a quad positive-edge triggered D-type flip-flop with individual data inputs (D_n) and complementary outputs (Q_n and $\bar{Q}_n$).

Features

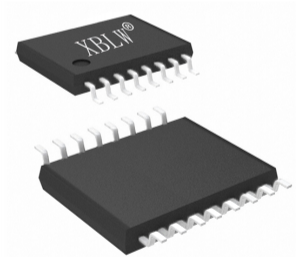
- Four edge-triggered D-type flip-flops
- Asynchronous master reset
- Specified from -40°C to $+125^{\circ}\text{C}$
- Packaging information: DIP-16/SOP-16/TSSOP-16



DIP-16



SOP-16



TSSOP-16

Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
XBLW SN74HC175N	DIP-16	74HC175N	Tube	1000Pcs/Box
XBLW SN74HC175DTR	SOP-16	74HC175	Tape	2500Pcs/Reel
XBLW SN74HC175TDTR	TSSOP-16	74HC175	Tape	3000Pcs/Reel

Block Diagram

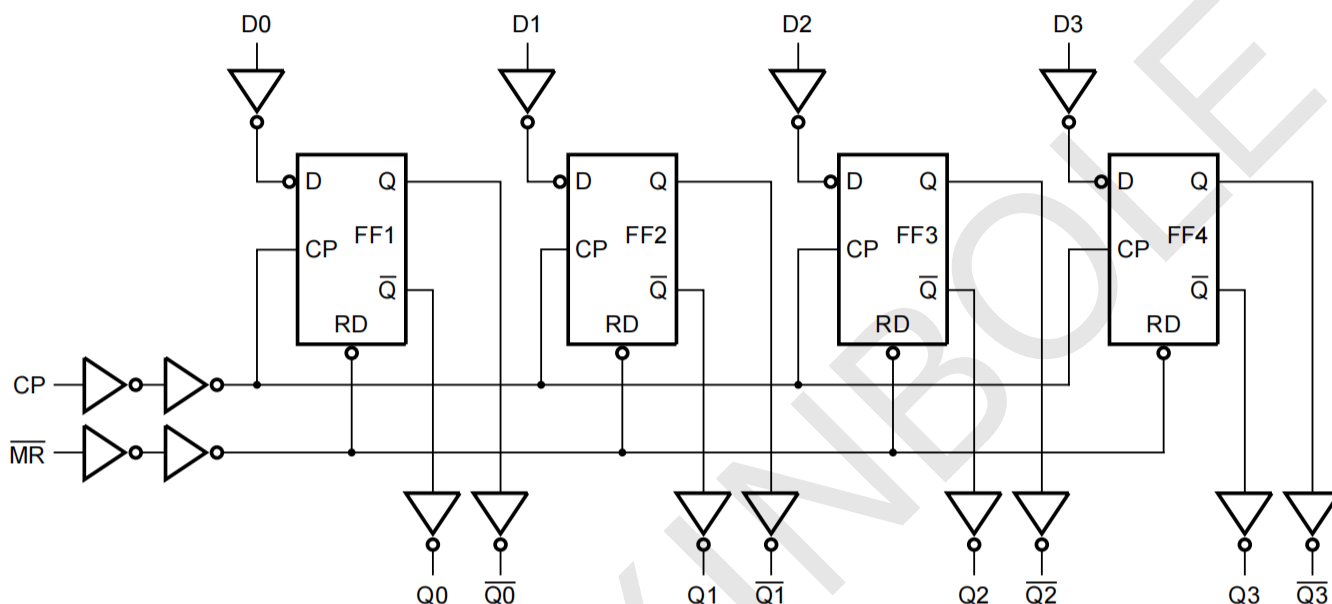
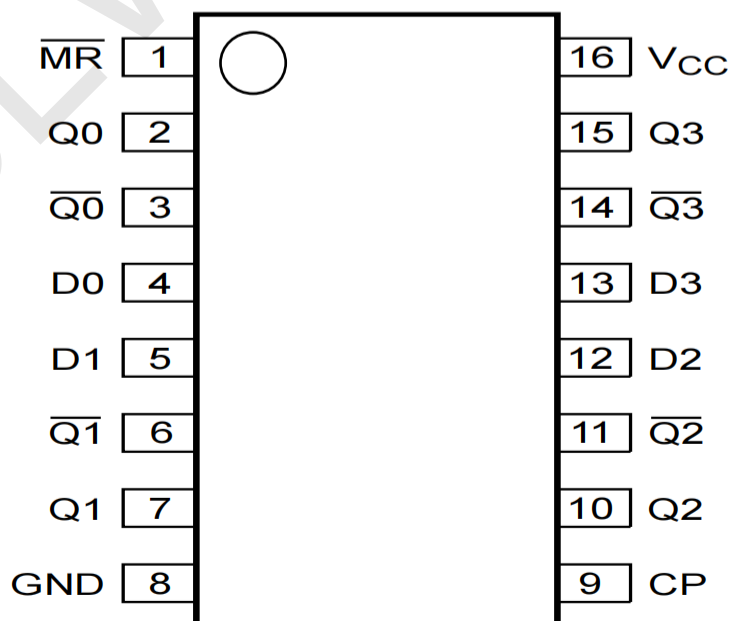


Figure 1. Logic diagram

Pin Configurations



Pin Description

Pin No.	Pin Name	Description
1	$\overline{MR}$	asynchronous master reset input (active LOW)
2	Q0	flip-flop output
3	$\overline{Q0}$	complementary flip-flop output
4	D0	data input
5	D1	data input
6	$\overline{Q1}$	complementary flip-flop output
7	Q1	flip-flop output
8	GND	ground (0V)
9	CP	clock input (LOW-to-HIGH edge-triggered)
10	$\overline{Q2}$	flip-flop output
11	Q2	complementary flip-flop output
12	D2	data input
13	D3	data input
14	$\overline{Q3}$	complementary flip-flop output
15	Q3	flip-flop output
16	Vcc	positive supply voltage

Function table

Operating mode	Inputs			Outputs	
	$\overline{MR}$	CP	Dn	Qn	$\overline{Qn}$
reset (clear)	L	X	X	L	H
load "1"	H	↑	h	H	L
load "0"	H	↑	l	L	H

Note:

H=HIGH voltage level; L=LOW voltage level;

X=don't care; ↑=LOW-to-HIGH clock transition;

h=HIGH voltage level one set-up time prior to the LOW-to-HIGH clock transition; l=LOW voltage level one set-up time prior to the LOW-to-HIGH clock transition.

Electrical Parameter

Absolute Maximum Ratings

($T_{amb}=25^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified)

Characteristic	Symbol	Conditions	Min.	Max.	Unit
supply voltage	V_{CC}	-	-0.5	+7.0	V
input clamping current	I_{IK}	$V_I < -0.5\text{V}$ or $V_I > V_{CC} + 0.5\text{V}$	-	+20	mA
output clamping current	I_{OK}	$V_O < -0.5\text{V}$ or $V_O > V_{CC} + 0.5\text{V}$	-	± 20	mA
output current	I_O	$V_O = -0.5\text{V}$ to $(V_{CC} + 0.5\text{V})$	-	± 25	mA
supply current	I_{CC}	-	-	+50	mA
ground current	I_{GND}	-	-50	-	mA
storage temperature	T_{stg}	-	-65	+150	$^{\circ}\text{C}$
total power dissipation	P_{tot}	-	-	500	mW
soldering temperature	T_L	10s	DIP		245 $^{\circ}\text{C}$
			SOP/TSSOP		260 $^{\circ}\text{C}$

Recommended Operating Conditions

(Voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
supply voltage	V_{CC}	-	2.0	5.0	6.0	V
input voltage	V_I	-	0	-	V_{CC}	V
output voltage	V_O	-	0	-	V_{CC}	V
ambient temperature	T_{amb}	-	-40	-	+125	$^{\circ}\text{C}$

DC Characteristics 1

($T_{amb}=25^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
HIGH-level input voltage	V_{IH}	$V_{CC}=2.0V$		1.5	1.2	-	V
		$V_{CC}=4.5V$		3.15	2.4	-	V
		$V_{CC}=6.0V$		4.2	3.2	-	V
LOW-level input voltage	V_{IL}	$V_{CC}=2.0V$		-	0.8	0.5	V
		$V_{CC}=4.5V$		-	2.1	1.35	V
		$V_{CC}=6.0V$		-	2.8	1.8	V
HIGH-level output voltage	V_{OH}	$V_I=V_{IH}$ or V_{IL}	$I_O=-20\mu A; V_{CC}=2.0V$	1.9	2.0	-	V
			$I_O=-20\mu A; V_{CC}=4.5V$	4.4	4.5	-	V
			$I_O=-20\mu A; V_{CC}=6.0V$	5.9	6.0	-	V
			$I_O=-4mA; V_{CC}=4.5V$	3.98	4.32	-	V
			$I_O=-5.2mA; V_{CC}=6.0V$	5.48	5.81	-	V
LOW-level output voltage	V_{OL}	$V_I=V_{IH}$ or V_{IL}	$I_O=20\mu A; V_{CC}=2.0V$	-	0	0.1	V
			$I_O=20\mu A; V_{CC}=4.5V$	-	0	0.1	V
			$I_O=20\mu A; V_{CC}=6.0V$	-	0	0.1	V
			$I_O=4mA; V_{CC}=4.5V$	-	0.15	0.26	V
			$I_O=5.2mA; V_{CC}=6.0V$	-	0.16	0.26	V
input leakage current	I_I	$V_I=V_{CC}$ or GND; $V_{CC}=6.0V$		-	-	± 1	μA
supply current	I_{CC}	$V_I=V_{CC}$ or GND; $I_O=0A; V_{CC}=6.0V$		-	-	1	μA

DC Characteristics 2

($T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
HIGH-level input voltage	V_{IH}	$V_{CC}=2.0V$		1.5	-	-	V
		$V_{CC}=4.5V$		3.15	-	-	V
		$V_{CC}=6.0V$		4.2	-	-	V
LOW-level input voltage	V_{IL}	$V_{CC}=2.0V$		-	-	0.5	V
		$V_{CC}=4.5V$		-	-	1.35	V
		$V_{CC}=6.0V$		-	-	1.8	V
HIGH-level output voltage	V_{OH}	$V_I=V_{IH} \text{ or } V_{IL}$	$I_O=-20\mu A; V_{CC}=2.0V$	1.9	-	-	V
			$I_O=-20\mu A; V_{CC}=4.5V$	4.4	-	-	V
			$I_O=-20\mu A; V_{CC}=6.0V$	5.9	-	-	V
			$I_O=-4mA; V_{CC}=4.5V$	3.84	-	-	V
			$I_O=-5.2mA; V_{CC}=6.0V$	5.34	-	-	V
LOW-level output voltage	V_{OL}	$V_I=V_{IH} \text{ or } V_{IL}$	$I_O=20\mu A; V_{CC}=2.0V$	-	-	0.1	V
			$I_O=20\mu A; V_{CC}=4.5V$	-	-	0.1	V
			$I_O=20\mu A; V_{CC}=6.0V$	-	-	0.1	V
			$I_O=4mA; V_{CC}=4.5V$	-	-	0.33	V
			$I_O=5.2mA; V_{CC}=6.0V$	-	-	0.33	V
input leakage current	I_I	$V_I=V_{CC} \text{ or } GND; V_{CC}=6.0V$		-	-	± 2	μA
supply current	I_{CC}	$V_I=V_{CC} \text{ or } GND; I_O=0A; V_{CC}=6.0V$		-	-	2	μA

DC Characteristics 3

($T_{amb} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
HIGH-level input voltage	V_{IH}	$V_{CC}=2.0V$		1.5	-	-	V
		$V_{CC}=4.5V$		3.15	-	-	V
		$V_{CC}=6.0V$		4.2	-	-	V
LOW-level input voltage	V_{IL}	$V_{CC}=2.0V$		-	-	0.5	V
		$V_{CC}=4.5V$		-	-	1.35	V
		$V_{CC}=6.0V$		-	-	1.8	V
HIGH-level output voltage	V_{OH}	$V_I=V_{IH} \text{ or } V_{IL}$	$I_O=-20\mu A; V_{CC}=2.0V$	1.9	-	-	V
			$I_O=-20\mu A; V_{CC}=4.5V$	4.4	-	-	V
			$I_O=-20\mu A; V_{CC}=6.0V$	5.9	-	-	V
			$I_O=-4mA; V_{CC}=4.5V$	3.7	-	-	V
			$I_O=-5.2mA; V_{CC}=6.0V$	5.2	-	-	V
LOW-level output voltage	V_{OL}	$V_I=V_{IH} \text{ or } V_{IL}$	$I_O=20\mu A; V_{CC}=2.0V$	-	-	0.1	V
			$I_O=20\mu A; V_{CC}=4.5V$	-	-	0.1	V
			$I_O=20\mu A; V_{CC}=6.0V$	-	-	0.1	V
			$I_O=4mA; V_{CC}=4.5V$	-	-	0.4	V
			$I_O=5.2mA; V_{CC}=6.0V$	-	-	0.4	V
input leakage current	I_I	$V_I=V_{CC} \text{ or } GND; V_{CC}=6.0V$		-	-	± 4	μA
supply current	I_{CC}	$V_I=V_{CC} \text{ or } GND; I_O=0A; V_{CC}=6.0V$		-	-	4	μA

AC Characteristics 1

($T_{amb}=25^{\circ}C$, $GND=0V$, $C_L=50pF$, unless otherwise specified)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
propagation delay	t_{PLH}/t_{PHL}	CP to $Q_n, \overline{Q_n}$; see Figure 4	$V_{CC}=2.0V$	-	55	175	ns
			$V_{CC}=4.5V$	-	50	35	ns
			$V_{CC}=5.0V$ $C_L= 15pF$	-	17	-	ns
			$V_{CC}=6.0V$	-	16	30	ns
HIGH to LOW propagation delay	t_{PHL}	$\overline{MR}$ to $Q_n, \overline{Q_n}$; see Figure 6	$V_{CC}=2.0V$	-	50	150	ns
			$V_{CC}=4.5V$	-	18	30	ns
			$V_{CC}=5.0V$ $C_L= 15pF$	-	15	-	ns
			$V_{CC}=6.0V$	-	14	26	ns
transition time	t_t	Q_n output; see Figure 4	$V_{CC}=2.0V$	-	19	75	ns
			$V_{CC}=4.5V$	-	7	15	ns
			$V_{CC}=6.0V$	-	6	13	ns
pulse width	t_w	CP input HIGH or LOW; see Figure 4	$V_{CC}=2.0V$	80	22	-	ns
			$V_{CC}=4.5V$	16	8	-	ns
			$V_{CC}=6.0V$	14	6	-	ns
		$\overline{MR}$ input LOW; see Figure 6	$V_{CC}=2.0V$	80	19	-	ns
			$V_{CC}=4.5V$	16	7	-	ns
			$V_{CC}=6.0V$	14	6	-	ns
recovery time	t_{rec}	$\overline{MR}$ to CP; see Figure 6	$V_{CC}=2.0V$	5	-33	-	ns
			$V_{CC}=4.5V$	5	-12	-	ns
			$V_{CC}=6.0V$	5	-10	-	ns
set-up time	t_{su}	D_n to CP; see Figure 4	$V_{CC}=2.0V$	80	3	-	ns
			$V_{CC}=4.5V$	16	1	-	ns
			$V_{CC}=6.0V$	14	1	-	ns
hold time	t_h	D_n to CP; see Figure 4	$V_{CC}=2.0V$	25	2	-	ns
			$V_{CC}=4.5V$	5	0	-	ns
			$V_{CC}=6.0V$	4	0	-	ns
maximum frequency	f_{max}	CP input; see Figure 4	$V_{CC}=2.0V$	6	25	-	ns
			$V_{CC}=4.5V$	30	75	-	ns
			$V_{CC}=5.0V$ $C_L= 15pF$	-	83	-	ns
			$V_{CC}=6.0V$	35	89	-	ns

AC Characteristics 2

($T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ GND=0V CL=50pF unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
propagation delay	t_{PLH}/t_{PHL}	CP to $Q_n, \bar{Q}_n$; see Figure 4	$V_{CC}=2.0V$	-	-	220 ns
			$V_{CC}=4.5V$	-	-	44 ns
			$V_{CC}=6.0V$	-	-	37 ns
HIGH to LOW propagation delay	t_{PHL}	$\bar{MR}$ to $Q_n, \bar{Q}_n$; see Figure 6	$V_{CC}=2.0V$	-	-	190 ns
			$V_{CC}=4.5V$	-	-	38 ns
			$V_{CC}=6.0V$	-	-	33 ns
transition time	t_t	Q_n output; see Figure 4	$V_{CC}=2.0V$	-	-	95 ns
			$V_{CC}=4.5V$	-	-	19 ns
			$V_{CC}=6.0V$	-	-	16 ns
pulse width	t_w	CP input HIGH or LOW; see Figure 4	$V_{CC}=2.0V$	100	-	- ns
			$V_{CC}=4.5V$	20	-	- ns
			$V_{CC}=6.0V$	17	-	- ns
		$\bar{MR}$ input LOW; see Figure 6	$V_{CC}=2.0V$	100	-	- ns
			$V_{CC}=4.5V$	20	-	- ns
			$V_{CC}=6.0V$	17	-	- ns
recovery time	t_{rec}	$\bar{MR}$ to CP; see Figure 6	$V_{CC}=2.0V$	5	-	- ns
			$V_{CC}=4.5V$	5	-	- ns
			$V_{CC}=6.0V$	5	-	- ns
set-up time	t_{su}	Dn to CP; see Figure 4	$V_{CC}=2.0V$	100	-	- ns
			$V_{CC}=4.5V$	20	-	- ns
			$V_{CC}=6.0V$	17	-	- ns
hold time	t_h	Dn to CP; see Figure 4	$V_{CC}=2.0V$	30	-	- ns
			$V_{CC}=4.5V$	6	-	- ns
			$V_{CC}=6.0V$	5	-	- ns
maximum frequency	f_{max}	CP input; see Figure 4	$V_{CC}=2.0V$	4.8	-	- ns
			$V_{CC}=4.5V$	24	-	- ns
			$V_{CC}=6.0V$	28	-	- ns

AC Characteristics 3

($T_{amb} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ GND=0V $C_L=50\text{pF}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
propagation delay	t_{PLH}/t_{PHL}	CP to $Q_n, \bar{Q}_n$; see Figure 4	$V_{CC}=2.0\text{V}$	-	-	265 ns
			$V_{CC}=4.5\text{V}$	-	-	53 ns
			$V_{CC}=6.0\text{V}$	-	-	45 ns
HIGH to LOW propagation delay	t_{PHL}	$\bar{MR}$ to $Q_n, \bar{Q}_n$; see Figure 6	$V_{CC}=2.0\text{V}$	-	-	225 ns
			$V_{CC}=4.5\text{V}$	-	-	45 ns
			$V_{CC}=6.0\text{V}$	-	-	38 ns
transition time	t_t	Q_n output; see Figure 4	$V_{CC}=2.0\text{V}$	-	-	110 ns
			$V_{CC}=4.5\text{V}$	-	-	22 ns
			$V_{CC}=6.0\text{V}$	-	-	19 ns
pulse width	t_w	CP input HIGH or LOW; see Figure 4	$V_{CC}=2.0\text{V}$	120	-	- ns
			$V_{CC}=4.5\text{V}$	24	-	- ns
			$V_{CC}=6.0\text{V}$	20	-	- ns
		$\bar{MR}$ input LOW; see Figure 6	$V_{CC}=2.0\text{V}$	120	-	- ns
			$V_{CC}=4.5\text{V}$	24	-	- ns
			$V_{CC}=6.0\text{V}$	20	-	- ns
recovery time	t_{rec}	$\bar{MR}$ to CP; see Figure 6	$V_{CC}=2.0\text{V}$	5	-	- ns
			$V_{CC}=4.5\text{V}$	5	-	- ns
			$V_{CC}=6.0\text{V}$	5	-	- ns
set-up time	t_{su}	Dn to CP; see Figure 4	$V_{CC}=2.0\text{V}$	120	-	- ns
			$V_{CC}=4.5\text{V}$	24	-	- ns
			$V_{CC}=6.0\text{V}$	20	-	- ns
hold time	t_h	Dn to CP; see Figure 4	$V_{CC}=2.0\text{V}$	40	-	- ns
			$V_{CC}=4.5\text{V}$	8	-	- ns
			$V_{CC}=6.0\text{V}$	7	-	- ns
maximum frequency	f_{max}	CP input; see Figure 4	$V_{CC}=2.0\text{V}$	4	-	- ns
			$V_{CC}=4.5\text{V}$	20	-	- ns
			$V_{CC}=6.0\text{V}$	24	-	- ns

Testing Circuit

AC Testing Circuit

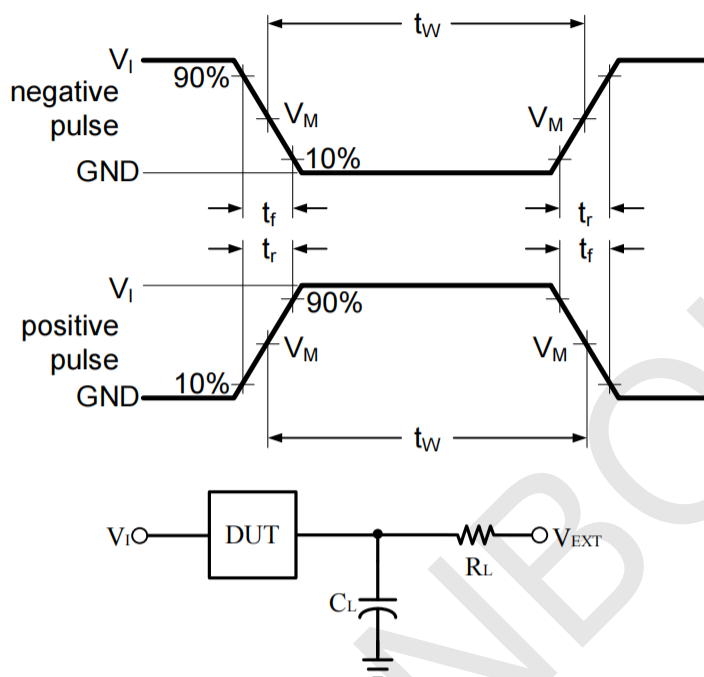


Figure 3. Test circuit for measuring switching times

Definitions for test circuit:
 C_L includes probe and jig capacitance

AC Testing Waveforms

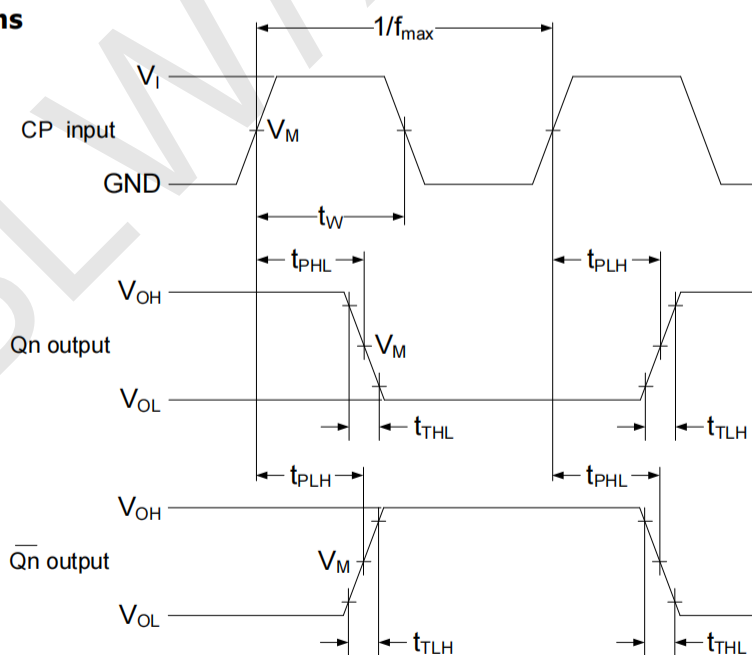


Figure 4. Input to output propagation delay, output transition time,
clock input pulse width and maximum frequency

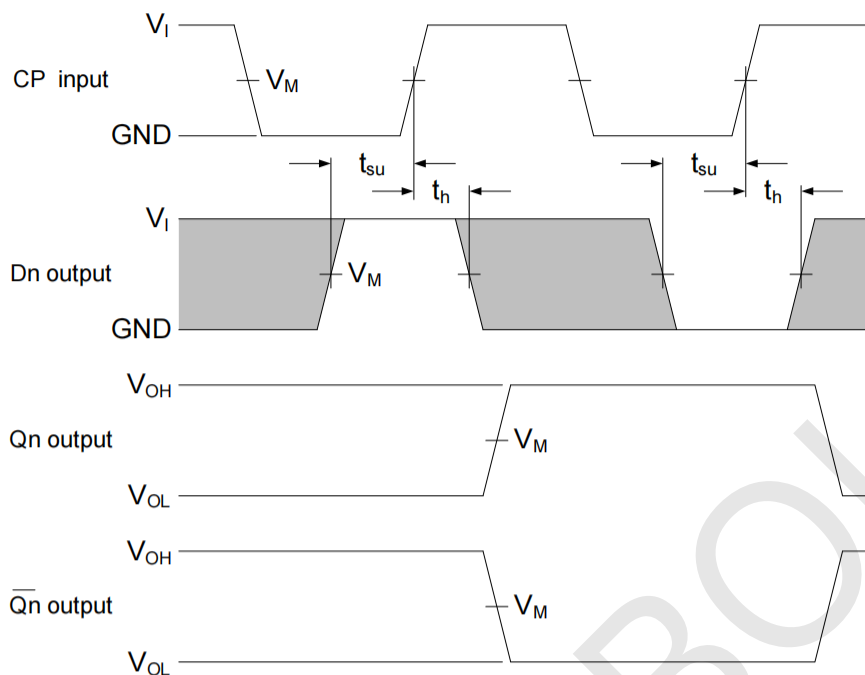


Figure 5. Data set-up and hold times for data input

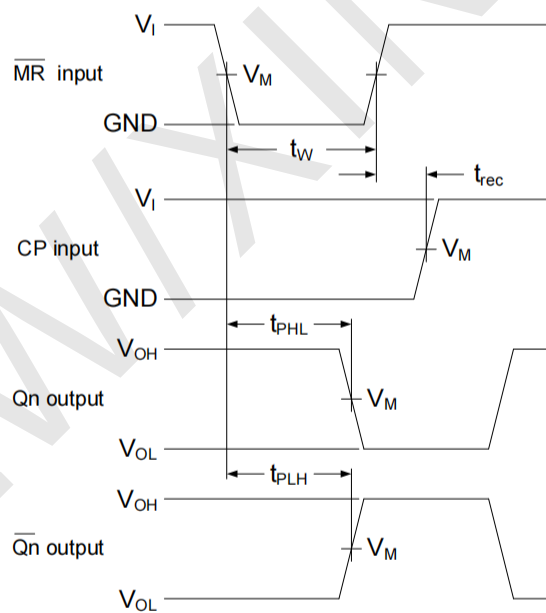


Figure 6. Master reset to output propagation delays, master reset pulse width and master reset to clock recovery time

Measurement Points

Type	Input		Output
	V_I	V_M	V_M
SN74HC175	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$

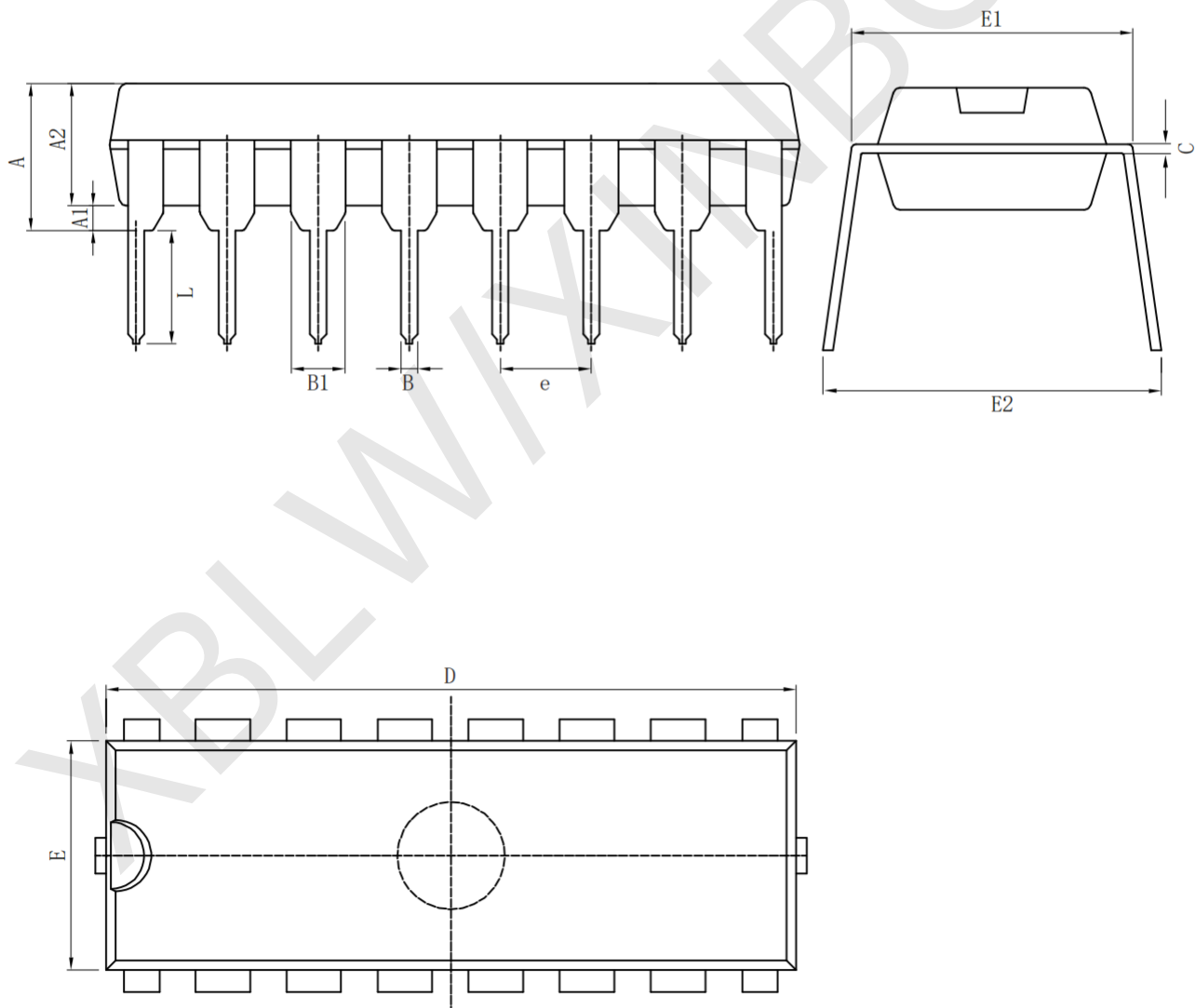
Test Data

Type	Input		Load		Test
	V_I	t_r, t_f	C_L	R_L	
SN74HC175	V_{CC}	3.0ns	15pF, 50pF	1k Ω	t_{PLH}, t_{PHL}

Package Information

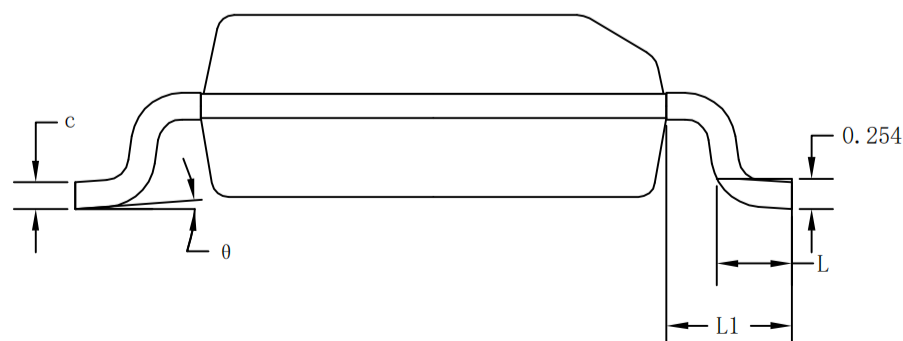
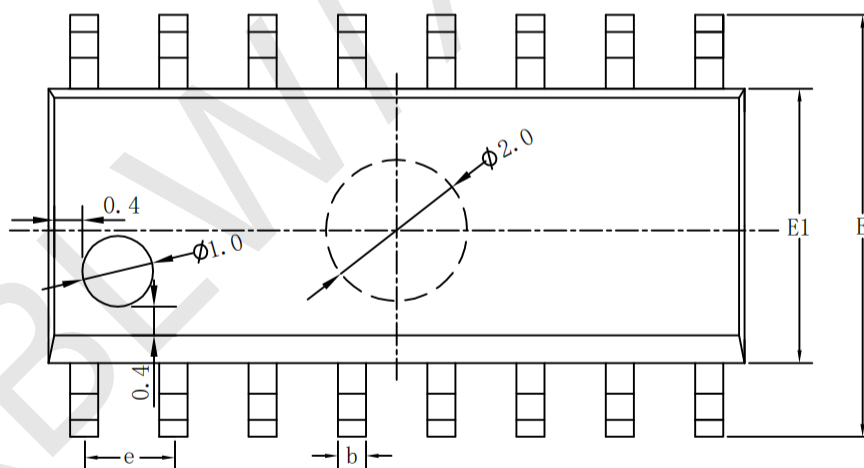
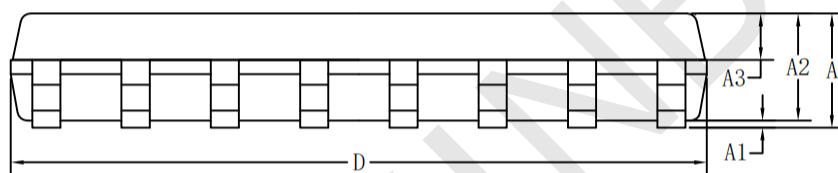
· DIP-16

Symbol	Size	Dimensions In Millimeters		Symbol	Size	Dimensions In Inches	
		Min(mm)	Max(mm)			Min(in)	Max(in)
A		3.710	4.310	A		0.146	0.170
A1		0.510		A1		0.020	
A2		3.200	3.600	A2		0.126	0.142
B		0.380	0.570	B		0.015	0.022
B1		1.524 (BSC)		B1		0.060 (BSC)	
C		0.204	0.360	C		0.008	0.014
D		18.80	19.20	D		0.740	0.756
E		6.200	6.600	E		0.244	0.260
E1		7.320	7.920	E1		0.288	0.312
e		2.540 (BSC)		e		0.100 (BSC)	
L		3.000	3.600	L		0.118	0.142
E2		8.400	9.000	E2		0.331	0.354



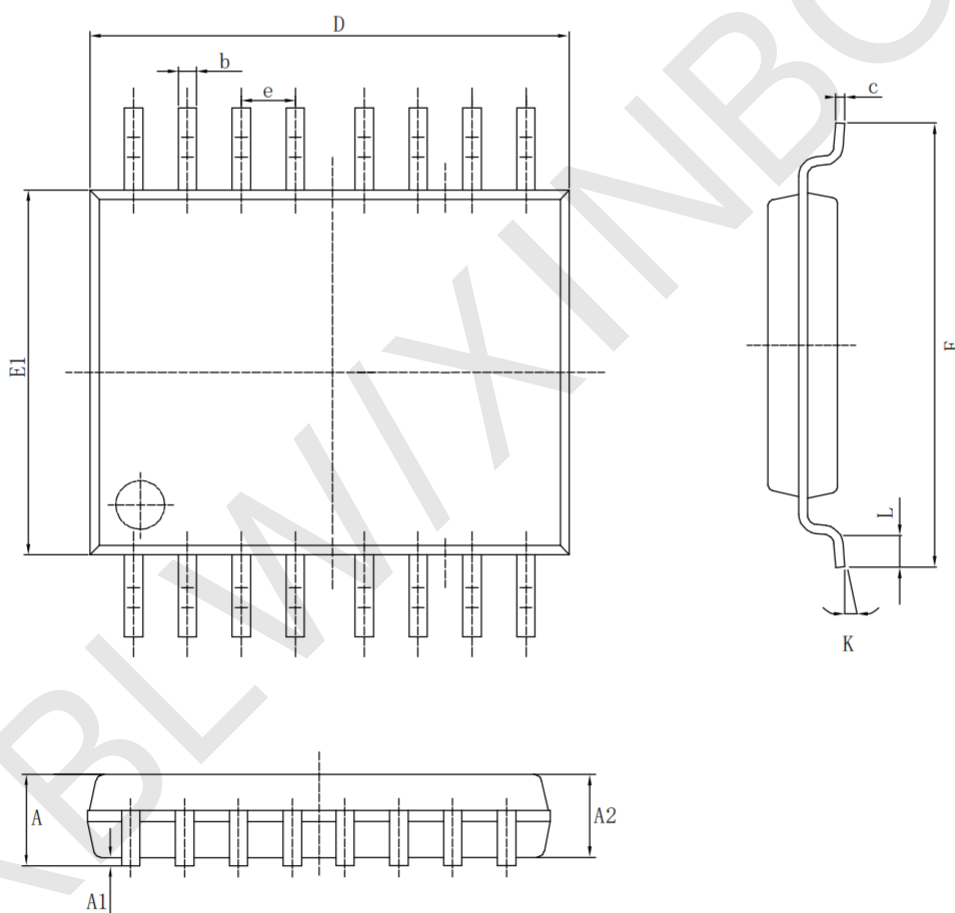
· SOP-16

Size Symbol	Dimensions In Millimeters			Size Symbol	Dimensions In Inches		
	Min (mm)	Nom (mm)	Max (mm)		Min (in)	Nom (in)	Max (in)
A	1.500	1.600	1.700	A	0.059	0.063	0.067
A1	0.100	0.150	0.250	A1	0.004	0.006	0.010
A2	1.400	1.450	1.500	A2	0.055	0.057	0.059
A3	0.600	0.650	0.700	A3	0.024	0.026	0.028
b	0.300	0.400	0.500	b	0.012	0.016	0.020
c	0.150	0.200	0.250	c	0.006	0.008	0.010
D	9.800	9.900	10.00	D	0.386	0.390	0.394
E	5.800	6.000	6.200	E	0.228	0.236	0.244
E1	3.850	3.900	3.950	E1	0.152	0.154	0.156
e	1.27 (BSC)			e	0.050 (BSC)		
L	0.500	0.600	0.700	L	0.020	0.024	0.028
L1	1.05 (BSC)			L1	0.041 (BSC)		
θ	0°	4°	8°	θ	0°	4°	8°



· TSSOP-16

Size Symbol	Dimensions In Millimeters		Size Symbol	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
A		1.200	A		0.047
A1	0.050	0.150	A1	0.002	0.006
A2	0.800	1.050	A2	0.031	0.041
b	0.190	0.300	b	0.007	0.012
c	0.090	0.200	c	0.004	0.0089
D	4.900	5.100	D	0.193	0.201
E	6.200	6.600	E	0.244	0.260
E1	4.300	4.480	E1	0.169	0.176
e	0.65 (BSC)		e	0.0256 (BSC)	
K	0°	8°	K	0°	8°
L	0.450	0.750	L	0.018	0.030



Statement

- XBLW reserves the right to modify the product manual without prior notice! Before placing an order, customers need to confirm whether the obtained information is the latest version and verify the completeness of the relevant information.
- Any semi-guide product is subject to failure or malfunction under specified conditions. It is the buyer's responsibility to comply with safety standards when using XBLW products for system design and whole machine manufacturing. And take the appropriate safety measures to avoid the potential in the risk of loss of personal injury or loss of property situation!
- XBLW product has not been licensed for life support, military and aerospace applications, and therefore XBLW is not responsible for any consequences arising from its use in these areas.
- If any or all XBLW products (including technical data, services) described or contained in this document are subject to any applicable local export control laws and regulations, they may not be exported without an export license from the relevant authorities in accordance with such laws.
- The specifications of any and all XBLW products described or contained in this document specify the performance, characteristics, and functionality of said products in their standalone state, but do not guarantee the performance, characteristics, and functionality of said products installed in Customer's products or equipment. In order to verify symptoms and conditions that cannot be evaluated in a standalone device, the Customer should ultimately evaluate and test the device installed in the Customer's product device.
- XBLW documentation is only allowed to be copied without any alteration of the content and with the relevant authorization. XBLW assumes no responsibility or liability for altered documents.
- XBLW is committed to becoming the preferred semiconductor brand for customers, and XBLW will strive to provide customers with better performance and better quality products.